

XP-002121182

AN - 1977-60023Y [34]

PR - JP19750157886 19751227

TI - Circuit board for resistor-printed circuits - has resistor layer
formed by simultaneous electrodeposition of boron nitride and nickel

IW - CIRCUIT BOARD RESISTOR PRINT CIRCUIT RESISTOR LAYER FORMING
SIMULTANEOUS ELECTRODEPOSIT BORON NITRIDE NICKEL

PA - (NITL) NITTO ELECTRIC IND CO

PN - JP52081559 A 19770708 DW197734 000pp

- JP58023954B B 19830518 DW198323 000pp

IC - H01C17/16 ; H05K1/16 ; H05K3/00

AB - J52081559 The board has a resistor layer formed by simultaneous
electrodeposition of boron nitride and nickel.

- Higher sheet resistance value is obtained reproducibly. The sheet
resistance of the resistor (e.g. 500 ohm/cm-3 is about ten times as
large as that of a nickel-phosphor alloy obtd. conventionally. The
sheet resistance is controllable by changing the amount of finely
divided boron nitride powder added to the electrolyte.